

## 300-MHz Quadrature Modulator

### Description

The IC U2793B is a 300-MHz quadrature modulator that uses TELEFUNKEN's advanced UHF process. It features low current consumption, single-ended RF ports and adjustment-free application, which makes the device suitable for all digital radio systems, e.g., GSM, PCN,

JDC and WLAN. As an option, output level and spurious products are adjustable at Pins 19 and 20. In conjunction with TEMIC's U2795B mixer, an up converter up to 2 GHz can be realized.

### Features

- Supply voltage: 5 V (typical)
- Low power consumption: 15 mA / 5 V (typical at 0 dBm output level)
- Output level and spurious products adjustable (optional)
- Excellent sideband suppression by means of duty cycle regeneration of the LO input signal
- Phase control loop for precise 90° phase shifting
- Power down mode
- Low LO input level: -15 dBm (typical)
- 50-Ω single-ended LO and RF port
- LO frequency range of 30 MHz to 300 MHz
- SSO-20 package

### Benefits

- Extended talk time due to increased battery life
- Few external components results in cost and board space saving
- Adjustment free hence saves time
- Modular system for different applications by adding U2795B reduces the costs

### Block Diagram

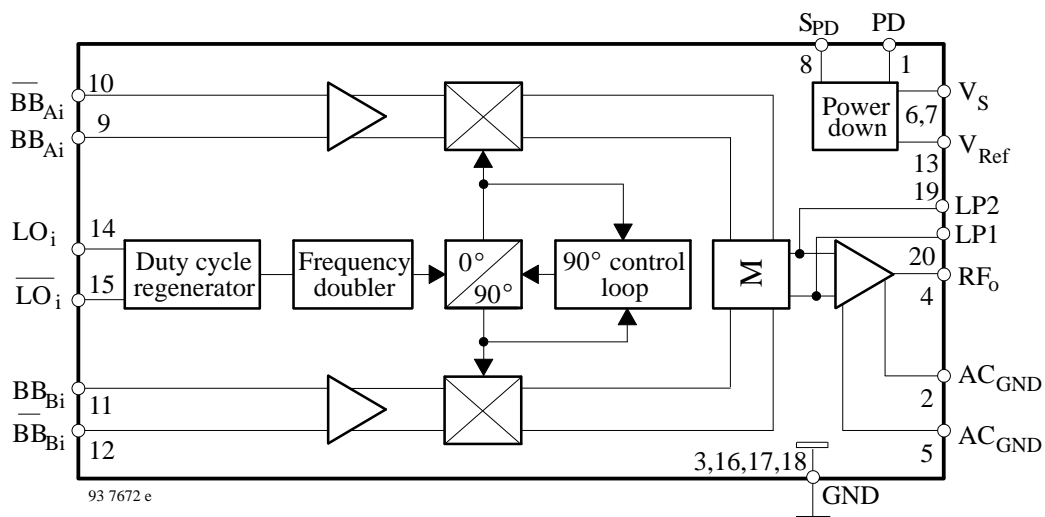


Figure 1.

## Pin description

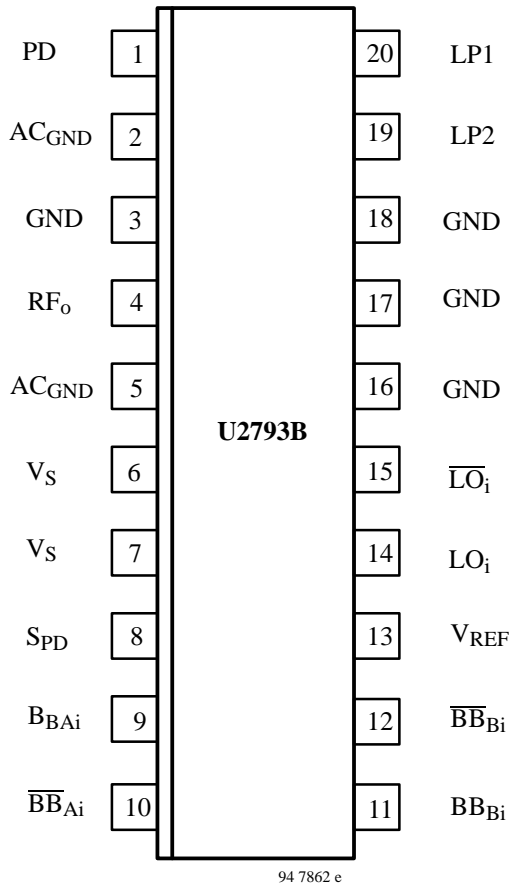


Figure 2.

Pin	Symbol	Function
1	PD	Power down port
2	AC <sub>GND</sub>	AC ground
3	GND	Ground
4	RF <sub>o</sub>	RF output
5	AC <sub>GND</sub>	AC ground
6,7	V <sub>S</sub>	Supply voltage
8	S <sub>PD</sub>	Settling time power down
9	BB <sub>Ai</sub>	Baseband input A
10	$\overline{\text{BB}}_{\text{Ai}}$	Baseband input A inverse
11	BB <sub>Bi</sub>	Baseband input B
12	$\overline{\text{BB}}_{\text{Bi}}$	Baseband input B inverse
13	V <sub>REF</sub>	Reference voltage (2.5 V)
14	LO <sub>i</sub>	Input LO
15	$\overline{\text{LO}}_{\text{i}}$	Input LO inverse, typically grounded
16,17,18	GND	Ground
19	LP2	Output low pass and power control
20	LP1	Output low pass and power control

## Absolute maximum ratings

Parameters	Symbol	Value	Unit
Supply voltage Pins 6 and 7	V <sub>S</sub>	6	V
Input voltage Pins 9, 10, 11, 12, 14 and 15	V <sub>i</sub>	0 to V <sub>S</sub>	V
Junction temperature	T <sub>j</sub>	125	°C
Storage temperature range	T <sub>stg</sub>	-40 to +125	°C

## Operating range

Parameters	Symbol	Value	Unit
Supply voltage Pins 6 and 7	V <sub>S</sub>	4.5 to 5.5	V
Ambient temperature range	T <sub>amb</sub>	-40 to +85	°C

## Thermal resistance

Parameters	Symbol	Value	Unit
Junction ambient SSO-20	R <sub>thja</sub>	140	K/W

## Electrical characteristics

Test conditions (unless otherwise specified);  $V_S = 5\text{ V}$ ,  $T_{\text{amb}} = 25^\circ\text{C}$ , referred to test circuit.  
 System impedance  $Z_0 = 50\ \Omega$ ,  $f_{\text{LO}} = 150\text{ MHz}$ ,  $P_{\text{LO}} = -15\text{ dBm}$ ,  $V_{\text{BBi}} = 1.0\text{ V}_{\text{ppdiff}}$ .

Parameters	Test conditions / Pin	Symbol	Min.	Typ.	Max.	Unit
Supply voltage range	Pins 6 and 7	$V_S$	4.5	5	5.5	V
Supply current	Pins 6 and 7	$I_S$		15		mA
<b>Baseband inputs</b>		<b>Pin 9–10, 11–12</b>				
Input voltage range (differential)		$V_{\text{BBi}}$		1000	1500	mVpp
Input impedance		$Z_{\text{BBi}}$		30		k $\Omega$
Input frequency range		$f_{\text{BBi}}$	0		50	MHz
<b>LO input</b>		<b>Pins 14 and 15</b>				
Frequency range		$f_{\text{LOi}}$	30		300	MHz
Input level <sup>1</sup>		$P_{\text{LOi}}$		-15	-5	dBm
Input impedance		$Z_{\text{iLO}}$		<sup>2)</sup>		$\Omega$
Voltage standing wave ratio		$\text{VSWR}_{\text{LO}}$		3.5		
Duty cycle range		$\text{DCR}_{\text{LO}}$	0.4		0.6	
<b>RF output</b>		<b>Pin 4</b>				
Output level	$f_{\text{LO}} = 150\text{ MHz}$ , $V_{\text{BBi}} = 1\text{ V}_{\text{ppdiff}}$ $f_{\text{LO}} = 50\text{ MHz}$ , $V_{\text{BBi}} = 0.3\text{ V}_{\text{ppdiff}}$	$P_{\text{RFo}}$	-3	-1 0		dBm
LO suppression	$P_{\text{LO}} = -20\text{ dBm}$	$\text{LO}_{\text{RFo}}$	32	45		dB
Voltage standing wave ratio		$\text{VSWR}_{\text{RF}}$		1.4	2	
Sideband suppression <sup>3</sup>		$\text{SBS}_{\text{RFo}}$	35	45		dB
Phase error <sup>4</sup>		$P_e$		<1		deg
Amplitude error		$A_e$		< $\pm 0.25$		dB
Noise floor	$V_{\text{BBi}} = 2\text{ V}$ , $\overline{V_{\text{BBi}}} = 3\text{ V}$ $V_{\text{BBi}} = \overline{V_{\text{BBi}}} = 2.5\text{ V}$	$N_{\text{FL}}$		-137 -143		dBm/Hz
<b>Power down mode</b>						
Supply current	$V_{\text{PD}} \leq 0.5\text{ V}$ , Pins 6, 7 $V_{\text{PD}} = 1\text{ V}$	$I_{\text{PD}}$		10	1	$\mu\text{A}$
Settling time	Pins 1 to 4 $C_{\text{SPD}} = 100\text{ pF}$ $C_{\text{LO}} = 100\text{ pF}$ , $C_{\text{RFo}} = 1\text{ nF}$	$t_{\text{SPD}}$		10		$\mu\text{s}$
<b>Switching voltage</b>		<b>Pin 1</b>				
Power		$V_{\text{PDon}}$	4			V
Power		$V_{\text{PDdown}}$			1	V
<b>Reference voltage</b>		<b>Pin 13</b>				
Voltage range		$V_{\text{Ref}}$		2.5 $\pm 5\%$		V
Output impedance		$Z_{\text{ORef}}$		30		$\Omega$

Note:

- <sup>1</sup> Required LO level is a function of the LO frequency.
- <sup>2</sup> The LO input impedance is consisting of a  $50\ \Omega$  resistor in series with a  $15\text{ pF}$  capacitor
- <sup>3</sup> With the Pins 19 and 20 spurious performance especially for low frequency application can be improved by adding a chip capacitor between LP1 and LP2. In conjunction with a parallel resistor the output level can be adjusted to the following mixer stage without degradation of LO suppression and noise performance which would decrease if the I/Q input level is reduced.
- <sup>4</sup> For  $T_{\text{amb}} = -40$  to  $+85^\circ\text{C}$  and  $V_S = 4.5$  to  $5.5\text{ V}$

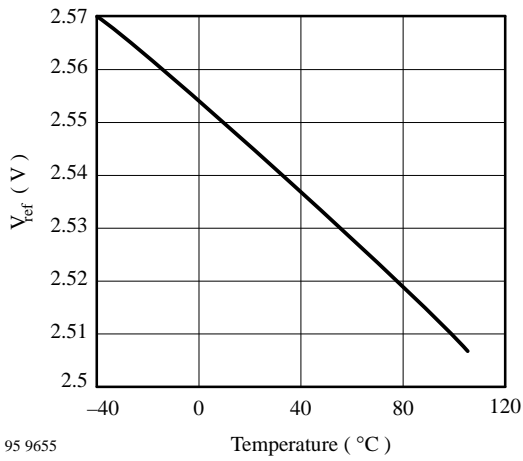


Figure 3. Reference voltage versus T<sub>amb</sub>

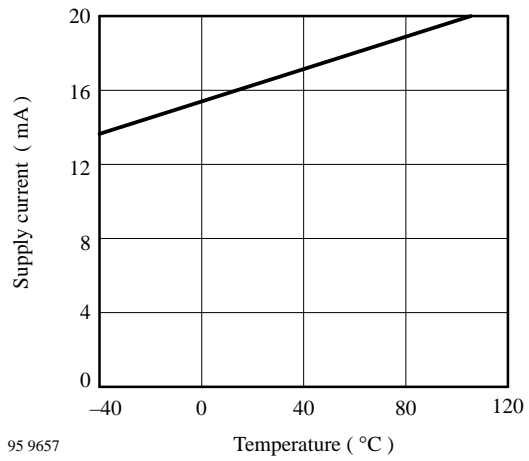


Figure 5. Supply current versus T<sub>amb</sub>

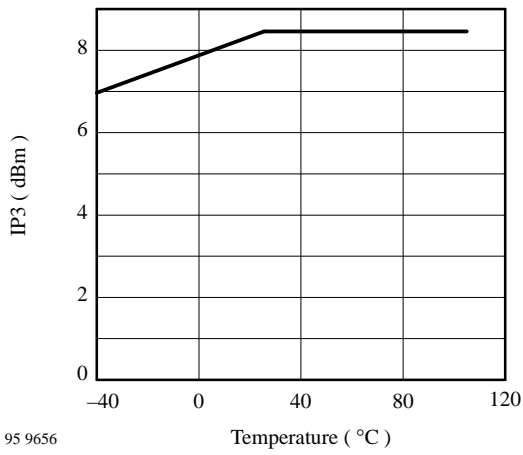


Figure 4. OIP3 versus T<sub>amb</sub>, LO = 150 MHz, level -10 dBm

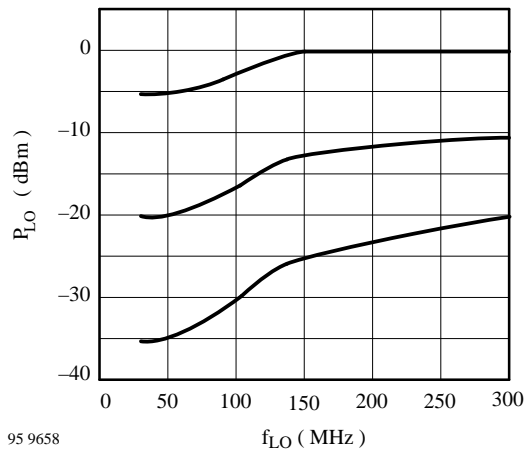


Figure 6. Recommended LO power range versus LO frequency at T<sub>amb</sub> = 25°C

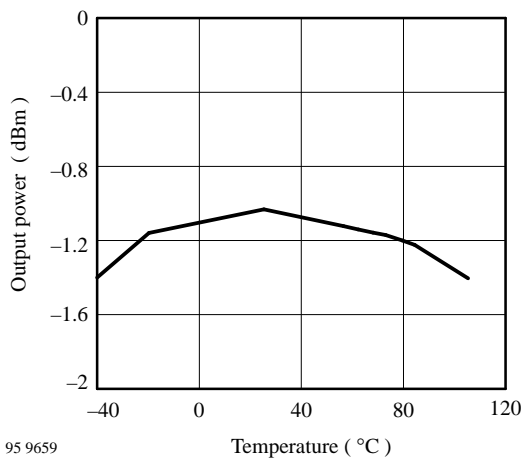


Figure 7. Figure 5 Output power versus  $T_{amb}$

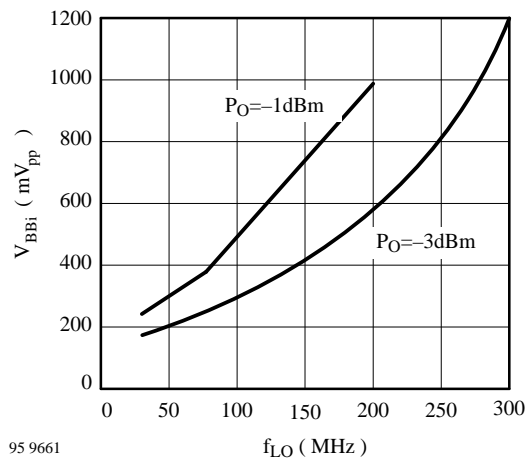


Figure 9. Typical required  $V_{BBi}$  input signal (differential) versus LO frequency for  $P_O = 1$  dBm and  $P_O = -3$  dBm

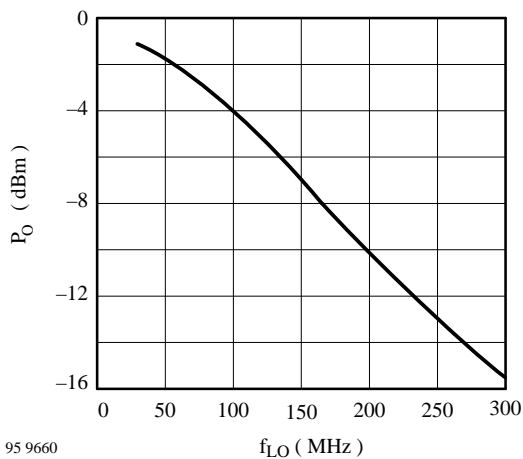
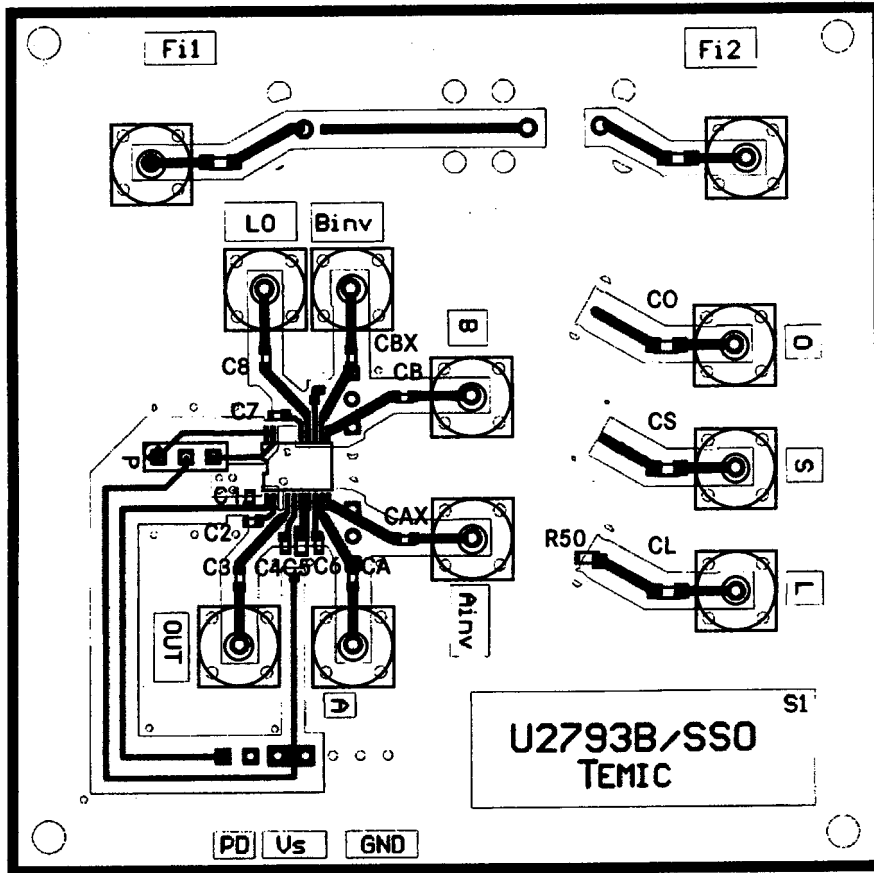


Figure 8. Typical output power vs. LO frequency at  $T_{amb} = 25^\circ\text{C}$ ,  $V_{BBi} = 250$  mV (differential)

## PCB layout



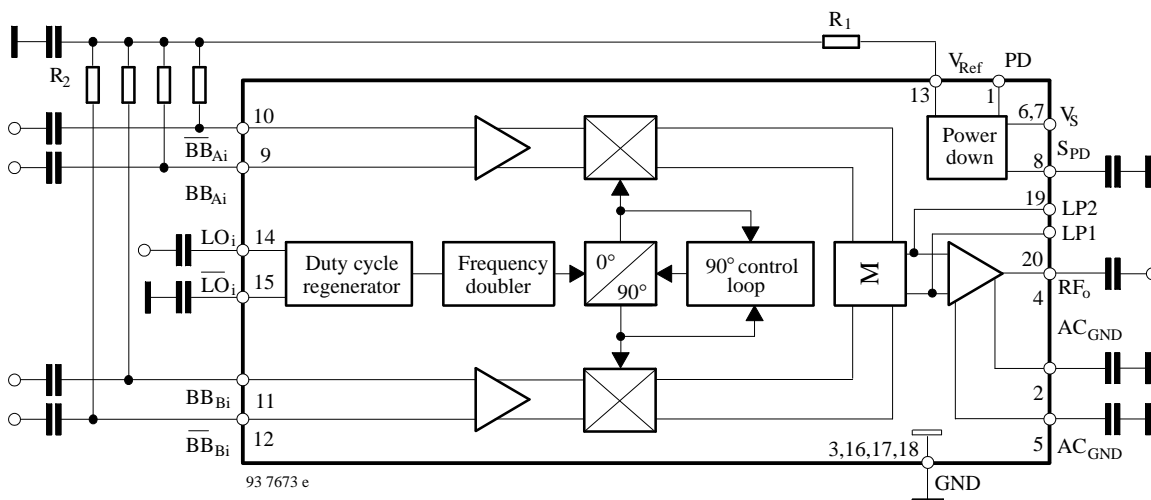
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Figure 10.

## Application circuit

Bias network for ac coupled baseband inputs ( $V_{BA}$ ,  $V_{BB}$ ).

$R_1 = 2.5 \text{ k}\Omega$ ,  $R_2 \leq 10 \text{ k}\Omega$  for  $\geq 35 \text{ dB}$  LO suppression which is in reference to  $< 2 \text{ mV}$  input offset.



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Figure 11.

## Evaluation board circuitry

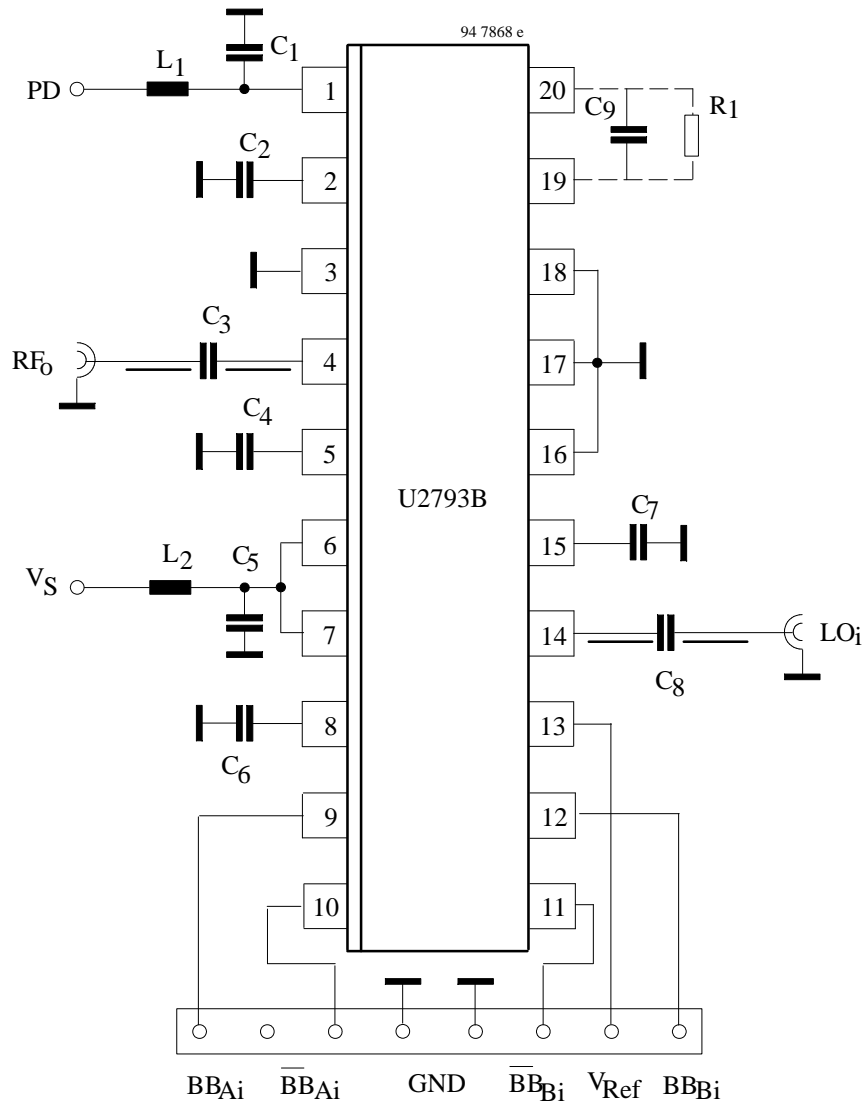
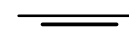



Figure 12.

Part list	
C1, C2, C3, C4, C6	1 nF
C7, C8	100 pF
C5	100 nF
C9, R1	1 to 10 pF
L1, L2	PCB Inductor
	50-Ω Microstrip
	optional

The above listed components result in a PD settling time of  $< 20 \mu\text{s}$ .  
Use of other component values will require consideration for time requirements in burst-mode applications.

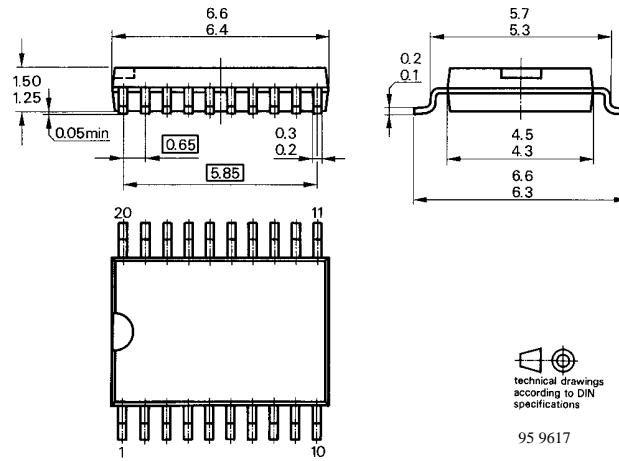
# U2793B-FS

# TEMIC

TELEFUNKEN Semiconductors

## Dimensions in mm

Package: SSO 20





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2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

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